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WO 2004/057674 A2 **US 5516704 A**

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(54) Abstract Title: **Laminated interconnects for opto-electronic device modules**

(57) A method of producing an encapsulated module of interconnected opto-electronic devices such as organic photovoltaic (PV) devices or organic light emitting diode (OLED) devices is provided, which comprises: forming a patterned anode layer 104; forming a layer of opto-electronically active material 108 over the patterned anode layer 104; forming a patterned cathode layer 110 over the layer of opto-electronically active material 108, to provide a device array 100 of opto-electronically active cells on the substrate; selectively removing portions of the layer of opto-electronically active material 108 so as to expose minor portions 104a of the anodes 104; forming a patterned interconnect layer 171 on an encapsulating sheet 172 in a pattern to define an array of interconnect pads 171; and laminating the patterned encapsulating sheet 170 over the array 100 of opto-electronically active cells whereby the exposed anode portions 104a are interconnected with the cathodes 110 of adjacent cells by the interconnect pads 171 and the interconnected cells are encapsulated by the encapsulating sheet 172 to form an encapsulated module. An encapsulated module thus produced is also provided. The method is particularly amenable to roll-to-roll manufacture.

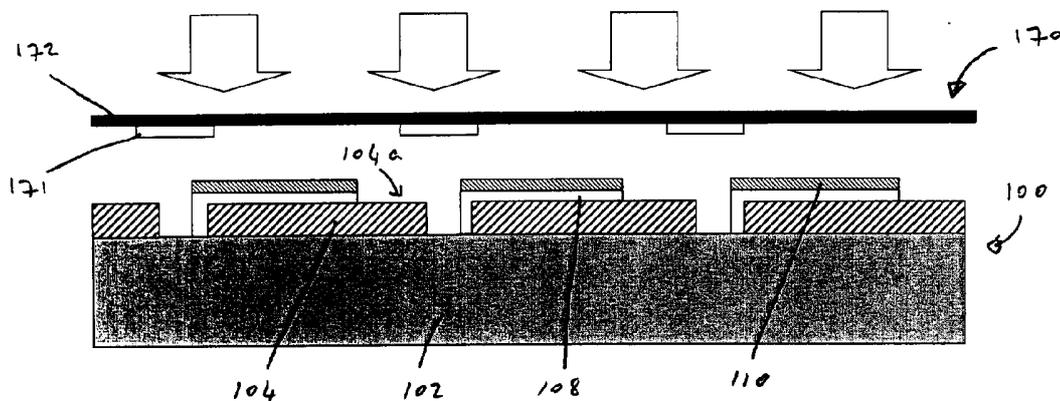


Figure 4

At least one drawing originally filed was informal and the print reproduced here is taken from a later filed formal copy.

This print takes account of replacement documents submitted after the date of filing to enable the application to comply with the formal requirements of the Patents Rules 1995

Original Printed on Recycled Paper

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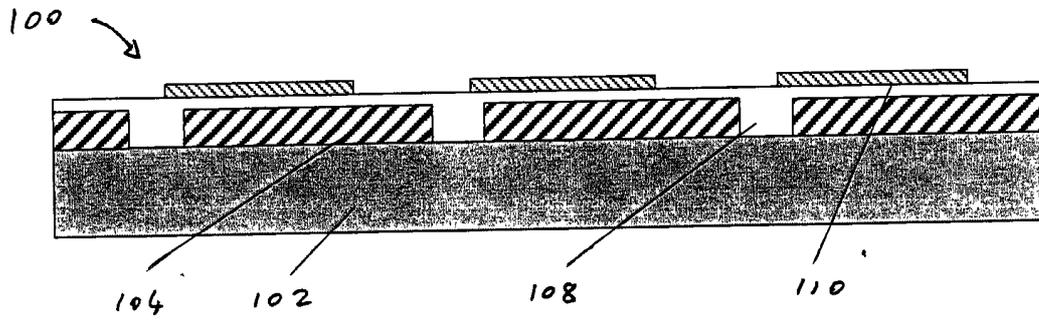


Figure 1

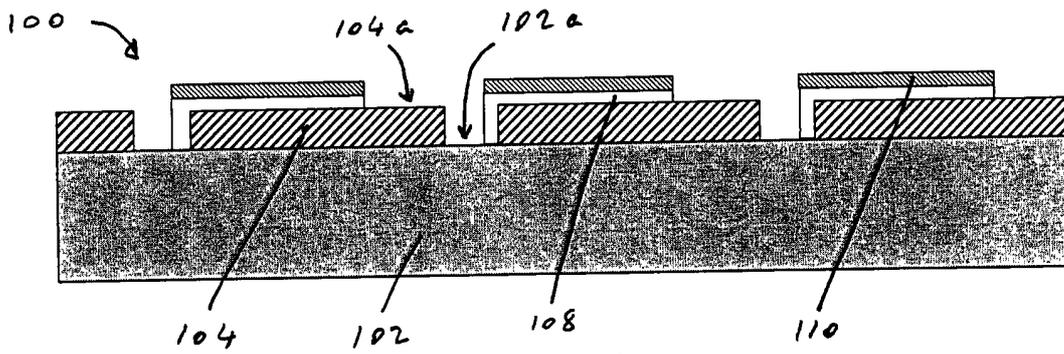


Figure 2

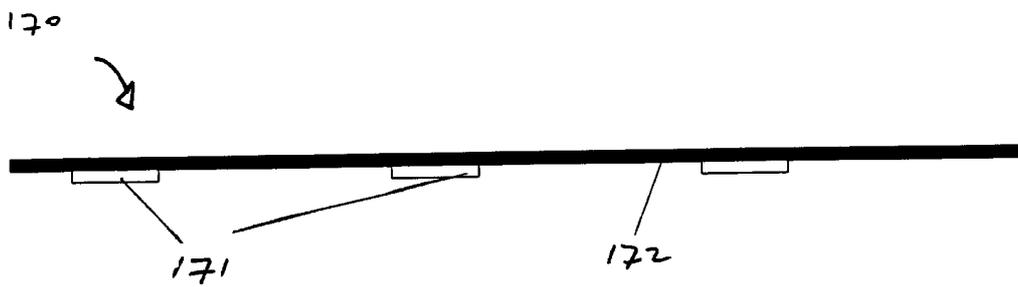


Figure 3

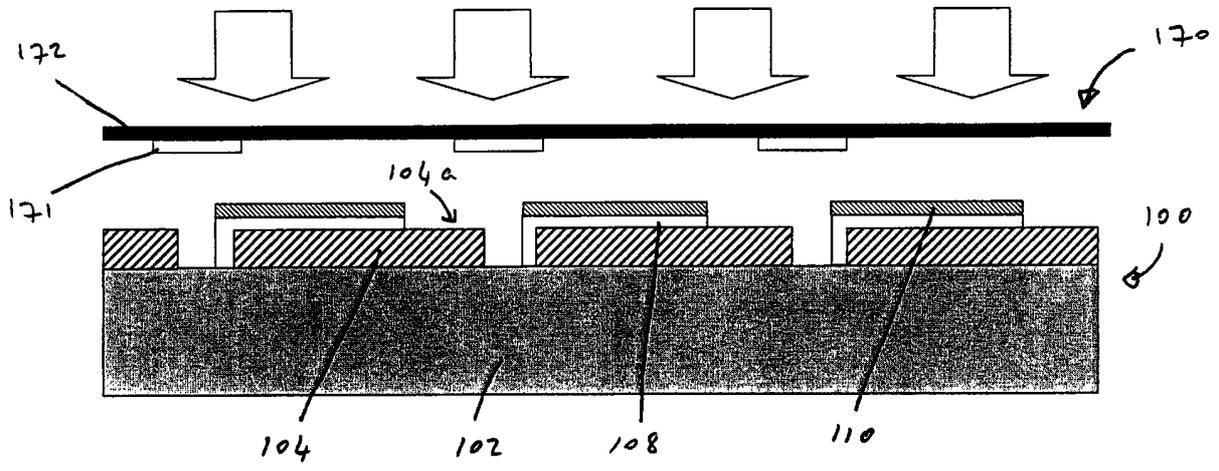


Figure 4

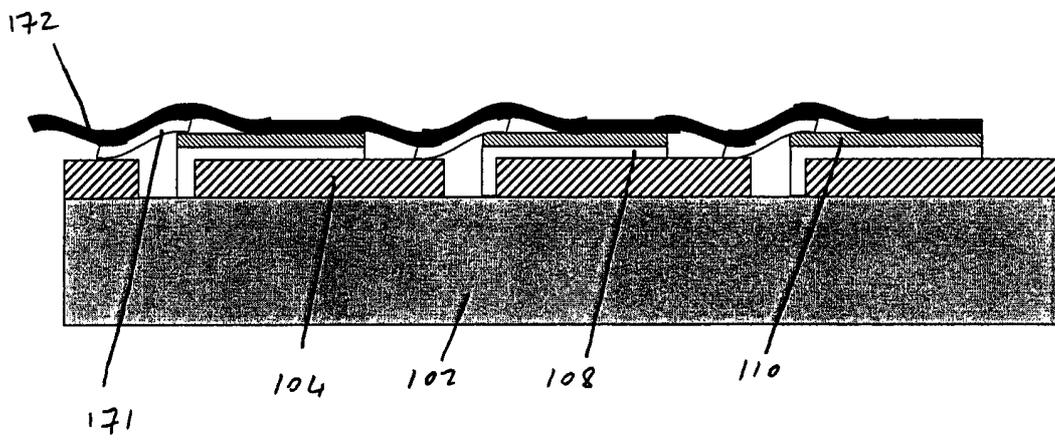


Figure 5

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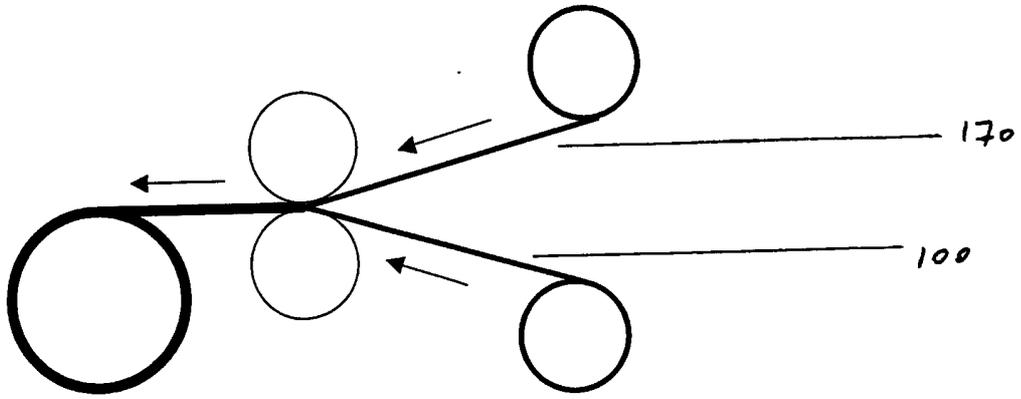


Figure 6

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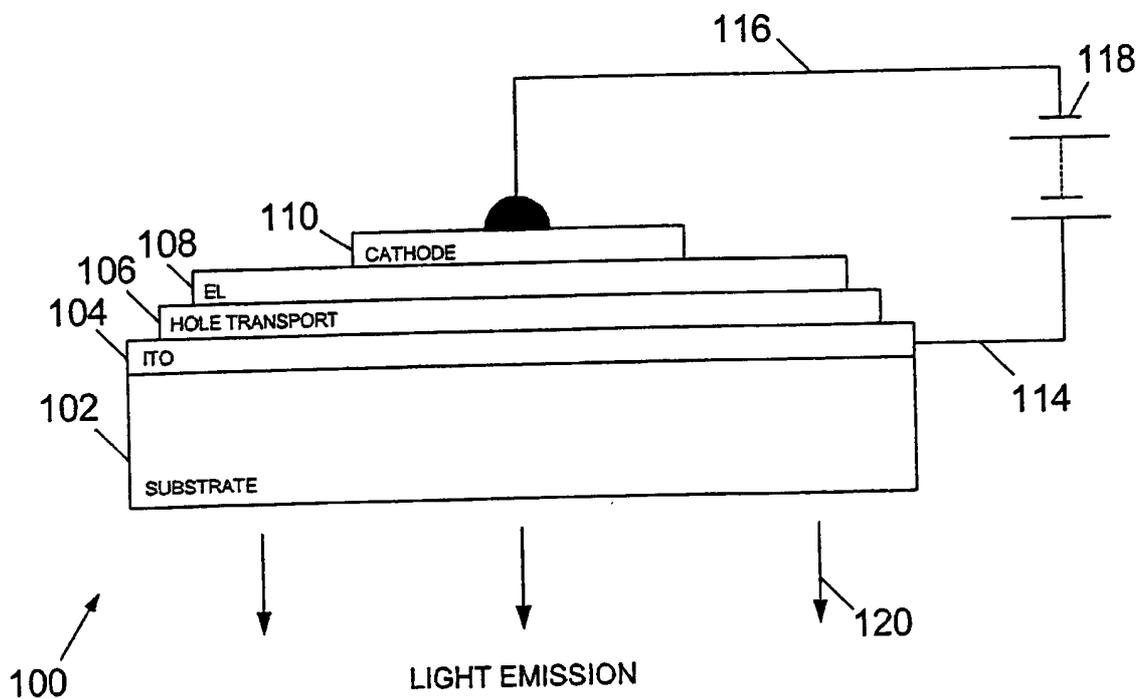


Figure 7a

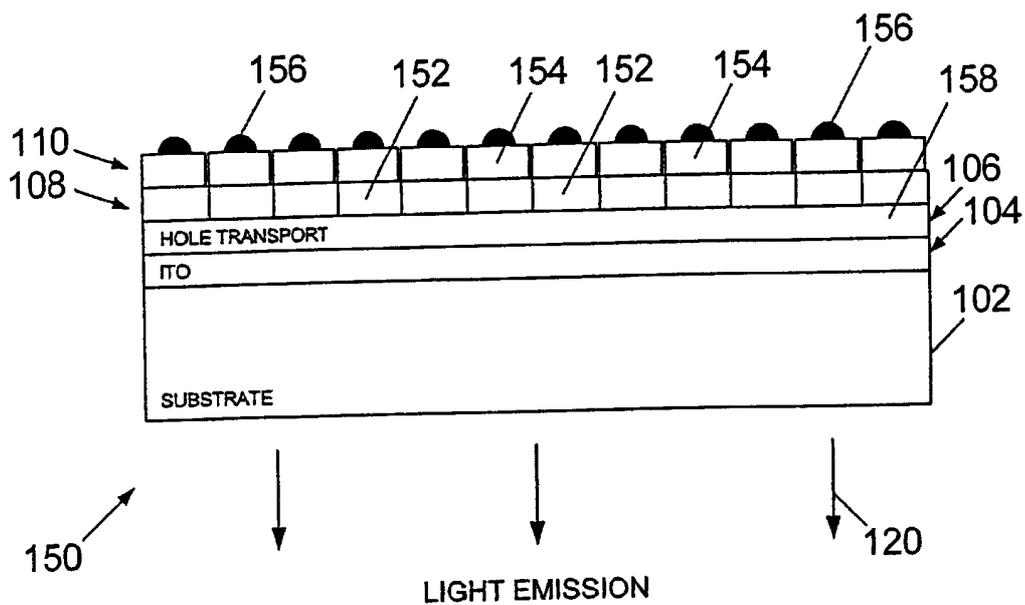


Figure 7b

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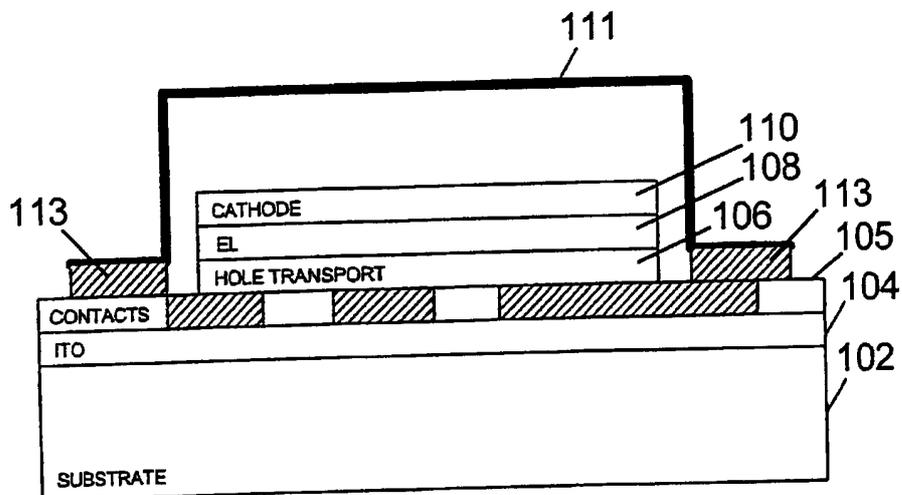


Figure 7c

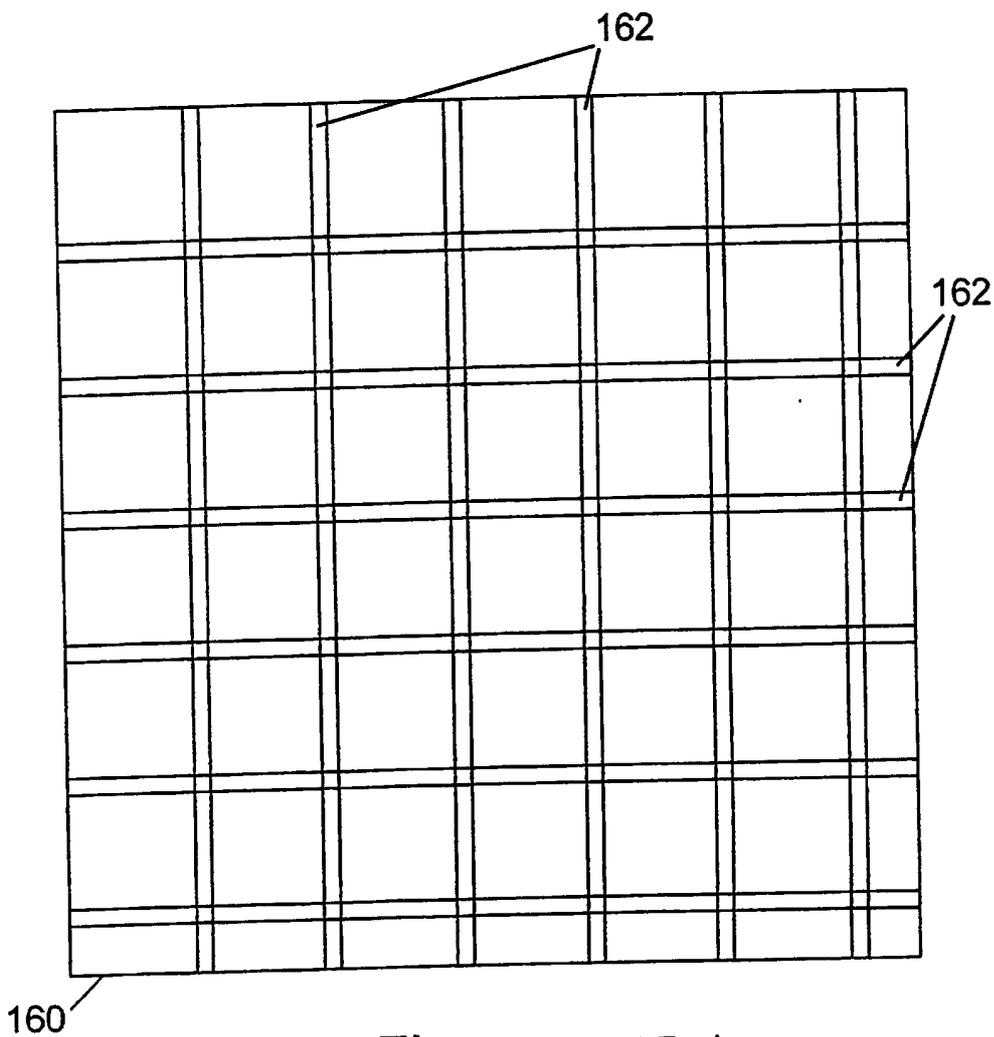
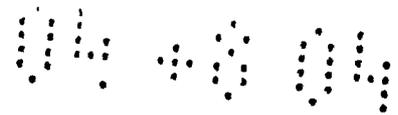


Figure 7d

LAMINATED INTERCONNECTS FOR ORGANIC OPTO-ELECTRONIC DEVICE
MODULES

This invention relates to a method for interconnecting and encapsulating individual opto-electronically active cells of organic opto-electronic devices such as organic photovoltaic (PV) or organic light emitting diode (OLED) devices, to form encapsulated modules. More particularly, the invention relates to a one-sheet lamination method that interconnects and encapsulates an array of opto-electronic devices formed on a substrate to form an encapsulated organic opto-electronic device module.

Organic opto-electronic devices such as organic PV devices and OLED devices generally comprise an opto-electronically active layer, formed of one or more layers of electroluminescent or light absorbing material, which active layer is sandwiched, usually with one or more layers of a hole transporting material, between a cathode layer and an anode layer. In the case of an organic PV device, the active layer is typically formed of one or more light absorbing layers of, for example, a blend of donor and acceptor polymers as disclosed in US5670791, a blend of a donor polymer with a small molecule acceptor such as [6,6]-phenyl C61-butyric acid methyl ester (PCBM) or a blend of small molecules. An optional hole collecting layer of a material such as polystyrene-sulphonate-doped polyethylene-dioxythiophene (PEDOT:PSS) may be provided between the anode layer and the active layer. For an OLED device, the active layer is typically formed of one or more electroluminescent layers comprising a light emitting material such as a light emitting polymer (LEP), for example poly(p-phenylenevinylene) (PPV), or a light emitting low molecular weight (small-molecule) material such as aluminium tris (8-hydroxyquinoline) (Alq₃). An optional hole injecting layer of a material such as PEDOT:PSS or a polyaniline derivative may be provided between the anode layer and the active layer.

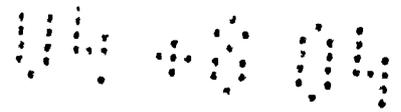


Organic opto-electronic devices such as organic PV devices and OLED devices can be fabricated by conventional techniques, generally by deposition of layers of the functional materials by spin-coating, spray coating, dip coating, doctor blade coating and the like. If a plurality of devices is formed on a single substrate, such deposition is followed by selective removal of the materials from areas between devices where they are not wanted, such as by plasma etching or laser ablation. For example, WO 01/39287 discloses selectively removing material from a PEDOT layer by plasma etching.

Alternatively, functional materials may be deposited selectively only in the areas where they are wanted. Suitable techniques for such selective deposition include inkjet printing as disclosed in EP 0880303, screen printing, and laser induced thermal imaging.

A cross-section through a basic structure 100 of a typical prior art organic opto-electronic device is shown in Figure 7a. A glass or plastic substrate 102 supports a transparent anode layer 104 of a transparent conductive oxide (TCO), for example indium tin oxide (ITO), on which is deposited a hole transport layer 106, an active layer 108, and a cathode 110. The hole transporting layer 106 helps match the hole energy levels of the anode layer 104 and the light active layer 108. Cathode layer 110 typically is of a metal such as aluminium and may include an additional layer immediately adjacent active layer 108, for example an alkali halide layer such as a layer of lithium fluoride, for improved electron energy level matching. Alternatively, cathode layer 110 may be located in direct contact with active layer 108 if it is of a metal such as calcium that has a lower work function than aluminium. Contact wires 114 and 116 to the anode and the cathode respectively provide a connection to a power source or storage cell 118.

Opto-electronic devices such as OLED devices may be deposited on a substrate in an array of opto-active cells. For example, in the case of an OLED device array, the cells are pixels to form a single or multi-colour pixelated display. As is known, in such displays the individual elements are generally addressed and written to by activating row and/or column lines to select the pixels. Conversely, in the case of a PV device matrix, the cells are photo-active cells which are addressed and from which photo-



generated current is collected by conductive lines associated with rows and/or columns of the photo-active cells.

Figure 7b shows a cross-section through a prior art opto-electronic matrix 150, in which like elements to those of Figure 7a are indicated by like reference numerals. In the matrix 150, the opto-active layer 108 comprises a plurality of opto-active portions 152 and the cathode layer 110 comprises a plurality of mutually electrically insulated conductive lines 154, running into the page in Figure 7b, each with an associated contact 156. Likewise, the anode layer 104 also comprises a plurality of anode lines 158, of which only one is shown in Figure 7b, running at right angles to the cathode lines. Contacts (not shown in Figure 7b) are also provided for each anode line.

Figure 7c shows a simplified cross-section through a prior art opto-electronic matrix. Again, like elements to those of Figures 7a and 7b are indicated by like reference numerals. Since the opto-electronically active materials are susceptible to oxidation and moisture, the device is encapsulated in a metal can 111 which is attached by glue 113 onto contact layer 105, small glass beads within the glue preventing the contacts being shorted out.

A plurality of such opto-electronic devices may be fabricated on a single substrate 160, for example as shown in Figure 7d. This substrate is patterned using a photoresist and organic layers 106, 108 are then deposited by spin coating before cathode layer 110 is applied. However, since the spin coating technique is non-selective, that is it deposits a thin film of organic material uniformly across the substrate, material must afterwards be removed from where it is not wanted. In particular, the spin coated organic material must be removed from areas where the encapsulating can 111 will be attached to the substrate, and also from areas where electrical connections will be made to the devices. In Figure 7d, horizontal and vertical strips or scribe lines 162 indicate where material is to be removed for attaching the can 111. The organic material may be removed mechanically, by scraping, or by using a wet chemical photolithographic process (relatively long and expensive) but the preferred method for removing the organic material is by laser ablation.

WO 04/057674, the contents of which are herein incorporated by reference, discloses the formation of an array of interconnected devices by forming a plurality of devices on a substrate, depositing metal connectors through a shadow mask to electrically connect neighbouring devices and encapsulating the array with a glass cover carrying an epoxy adhesive.

The method of the invention allows interconnection and encapsulation to be performed in a single step, which is amenable to roll-to-roll processing.

Accordingly, in a first aspect, the present invention provides a method of producing an encapsulated module of interconnected opto-electronic devices, comprising:

forming a patterned first electrode layer on a substrate in a pattern to define an array of first electrodes;

forming a layer of opto-electronically active material over said patterned first electrode layer on said substrate so as to overlie at least major portions of said first electrodes;

forming over said layer of opto-electronically active material a patterned second electrode layer having an opposite polarity to the first electrode in a pattern to define an array of second electrodes corresponding to said first electrode array, wherein said first electrodes, second electrodes and opto-electronically active material between said first and second electrodes define an array of opto-electronically active cells on said substrate; wherein said layer of opto-electronically active material and said patterned second electrode layer are so formed as to overlie a major portion of each first electrode and such that a minor portion of each first electrode is not overlain by said patterned layer of opto-electronically active material and said second electrode layer;

forming a patterned interconnect layer on an encapsulating sheet in a pattern to define an array of interconnect pads for interconnecting exposed first electrode portions with second electrodes of adjacent cells;



laminating said patterned encapsulating sheet over said array of opto-electronically active cells so as to bring said interconnect pad array into contact with exposed first electrode portions and second electrodes of adjacent cells whereby said exposed first electrode portions are interconnected with said second electrodes of said adjacent cells by said interconnect pads and said interconnected cells are encapsulated by said encapsulating sheet to form an encapsulated module.

In another aspect, the present invention provides an encapsulated module of interconnected opto-electronic devices, comprising:

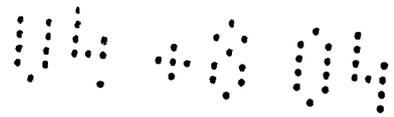
an array of opto-electronically active cells on a substrate, each cell comprising a first electrode layer formed on said substrate; a layer of opto-electronically active material formed over a major portion of said first electrode layer; a second electrode layer formed over said layer of opto-electronically active material and overlying a major portion of said first electrode layer whereby a minor portion of said first electrode layer is neither overlain by said layer of opto-electronically active material nor overlain by said second electrode layer; and

an encapsulating sheet having thereon an array of interconnects and laminated over said array of opto-electronically active cells;

wherein said cells are interconnected by said interconnects contacting said minor first electrode portion of one cell and said second electrode layer of another cell.

The invention may be extended to the interconnection of all types of organic opto-electronic devices, including, but not limited to, PV devices, photodetectors, transistors and OLEDs. Preferably, the opto-electronic device is an organic PV device or an OLED device.

According to the present invention, a device array is built on a substrate fabricated from glass, plastic, a glass/plastic laminate, ceramic or any other suitable substrate material. If desired, the substrate may additionally comprise one or more barrier layers such as ceramic layers.



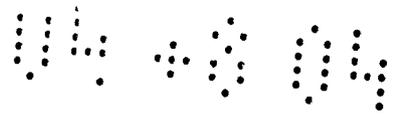
Preferably, the first electrode is an anode and the second electrode is a cathode, and the invention will be further described by reference to this preferred embodiment.

However, it will be appreciated that so-called upside-down devices may be constructed in accordance with the invention, in which the cathode is deposited on the substrate, as the first electrode, and the anode is deposited over the active layer, as the second electrode.

The substrate is coated with an anode layer formed of a transparent conductive oxide (TCO) such as indium tin oxide (ITO). The anode layer is patterned, by removing selected regions thereof in conventional manner, in order to define individual device anodes and any additional interconnect tracks. If desired, selected areas of the substrate may be further metallised in order to provide additional conducting tracks on the substrate surface.

The substrate coated with the patterned anode layer is then coated with a hole transport layer such as PEDOT:PSS, and may then be baked. The hole transport layer coated over the anode layer and substrate is then coated with active layer(s) of one or more active polymeric materials. The active layer(s) may consist of a blend of donor and acceptor polymers, a blend of a donor polymer with a small molecule acceptor such as PCBM, a blend of small molecules or other appropriate opto-electronic system. The hole transport layer (a conductive polymeric material such as PEDOT:PSS) and active polymeric layer may be deposited by any appropriate solution processing technique, such as, but not limited to, spin-coating, spray coating, inkjet printing, or screen printing.

Then, a cathode layer, consisting of one or more metallic layers, for example of aluminium, is deposited over the active layer. An alkali halide layer, such as LiF, may be deposited over the active layer prior to deposition of the metallic cathode layer. The cathode layer is patterned, preferably using a shadow mask, so that a cathode overlies a major portion of, but not all of, each anode in the patterned anode layer. A schematic cross section of a device array thus obtained is shown in Figure 1.



The active polymer and hole transport layers shown in Figure 1 are deposited to cover substantially the whole surface of the substrate. These layers are then patterned, by selectively removing the portions of these layers that overly the areas where interconnects are to be made to the anode areas or to other conducting tracks and pads, as shown in Figure 2. Thus, the portions of the active layers that overlie the portions of each anode that are not overlain by a cathode are removed, so as to expose a minor portion of each anode. Suitable techniques for selectively removing polymeric layer portions to pattern the active polymer and hole transport layers include laser ablation and plasma etching.

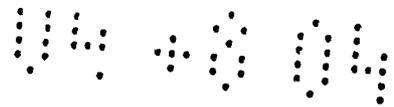
It will be appreciated that selective deposition techniques such as inkjet printing can be used to obviate the step of removing polymeric layer portions.

In a preferred embodiment, the anode layer comprises indium tin oxide (ITO), a hole transport layer of PEDOT:PSS is present between the ITO layer and the active layer, and the cathode layer comprises one or more metallic layers.

In a separate step, or in parallel with the preparation of the device array, an encapsulation and interconnect sheet is prepared. The sheet consists of a flexible plastic substrate (e.g. poly(ethylene terephthalate) (PET) or poly(ethylene naphthalate) (PEN)) on which barrier layers may optionally be deposited to reduce permeability to oxygen and water vapour. Suitable barrier layers include ceramic materials such as oxides, carbides or nitrides. A single barrier layer may be provided. For increased impermeability, alternating layers of plastic material and barrier material may also be provided on the sheet. Conducting interconnect pads (or tracks) are deposited on the plastic sheet, as shown in Figure 3.

The conducting interconnect pads may be formed on said sheet by such techniques as sputtering, shadow evaporation or screen printing, for example as:

- metals (e.g. aluminium) deposited by shadow evaporation or sputtering;
- ITO or other TCOs deposited by sputtering, and patterned by a photolithographic process;



- colloidal metal suspensions deposited by screen printing or other printing techniques; or
- highly conductive plastics, such as PEDOT:PSS, deposited by screen printing or other printing techniques.

In a preferred embodiment, the interconnect pads are of a conducting material selected from aluminium, ITO, a colloidal metal and PEDOT:PSS.

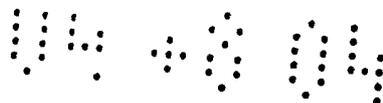
The completed device array is then placed in contact with the interconnect/encapsulation sheet and laminated thereto, preferably under application of pressure or heat, or both, so as to laminate the two sheets together, as shown in Figure 4.

In order to aid adhesion of the interconnect/encapsulation layer sheet to the device array, adhesives may be used. These may be ink-jet printed, screen printed or deposited by any other suitable technique onto the device array or, preferably, onto the interconnect/encapsulation sheet, or both. Conducting adhesives, such as colloidal metal suspensions in a polymeric binder, may be used to ensure a good connection between the interconnects and appropriate areas of the device layer.

Thus, the interconnects make contact with the cathodes and exposed ITO anodes or metallised tracks of the device array, and the encapsulation layer additionally protects the device array, giving environmental protection and increasing robustness. The complete laminated structure is shown in Figure 5.

The encapsulated module according to the invention may for example comprise an array of devices as shown in Figure 7b but modified such that the contacts 156 are arranged so as to connect a cathode with a neighbouring anode. The devices in the encapsulated module according to the invention may be interconnected in any desired configuration, for example as a two-dimensional array as shown in Figure 7d, or as a one-dimensional row.

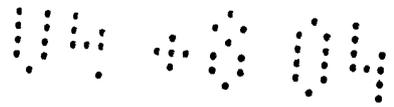
In the case of a solar cell array, the interconnect pads allow series connection of cells to give a module with an increased voltage output. The pads also allow parallel



connection to give a module with an increased current output. The module may include both parallel and series connections to give the optimum module output for a given application. Additional interconnects between the cell anodes and cathodes and the external connections to the module may also be provided.

The lamination technique of this invention provides a simplified means of forming interconnected arrays of devices that is applicable to rigid substrates (e.g. glass) or flexible substrates (e.g. plastic, plastic/thin glass or plastic/ceramic). Furthermore, if both the substrate and encapsulation sheet are flexible then this fabrication technique is amenable to high speed, large volume production by roll-to-roll manufacture, as illustrated in Figure 6. Accordingly, the patterned encapsulating sheet preferably is laminated over said array of opto-electronically active cells by a roll-to-roll manufacturing technique.

Figure 1 shows a schematic cross section of a device array 100 prior to selective removal of portions of active layer 108. A substrate 102 is coated with an anode layer 104 formed of a transparent conductive oxide (TCO). The anode layer 104 is patterned in conventional manner in order to define individual device anodes and any additional conducting tracks. The substrate 102 coated with the patterned anode layer 104 is then coated by depositing a hole transport layer such as PEDOT:PSS, baking, and coating the baked hole transport layer with the opto-electronically active layer 108, which may for example be formed of one or more polymeric or small molecule opto-active materials. Suitable techniques for applying the hole transport layer and active layer 108 include spin-coating, spray coating, inkjet printing, and screen printing. Suitable polymeric or small molecule opto-active materials include small molecules such as Alq₃ as disclosed in US 4,539,507; polymers such as poly(phenylene vinylenes) as disclosed in WO 90/13148 and polyarylenes such as polyphenylenes and polyfluorenes as disclosed in, for example, Adv. Mater. 2000, 12(23), 1737-1750; and dendrimers as disclosed in WO 02/067343. Where the devices according to the invention are OLEDs, the electroluminescent layer formed from the opto-active material may be fluorescent or phosphorescent.



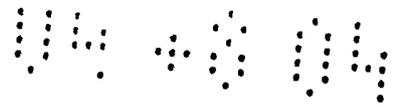
A metallic cathode layer 110 is deposited over the active layer 108, optionally after deposition of an intervening alkali halide layer. The cathode layer 110 is patterned, preferably using a shadow mask, so that a cathode overlies a major portion of, but not all of, each anode in the patterned anode layer.

Referring to Figure 2, the hole transport layer and active layer 108 in device array 100 are then patterned, by selectively removing the portions of the hole transport layer and active layer 108 that overlie the areas where interconnects are to be made to the anode areas or to other conducting tracks and pads. Thus, the portions of the hole transport layer and active layer 108 that overlie the portions of each anode 104 that are not overlain by a cathode 110 are removed, so as to expose a minor portion 104a of each anode. In addition, the portions of the hole transport layer and active layer 108 that overlie the portions 102a of the substrate 102 that are not overlain by a cathode 110 may also be removed. Suitable techniques for selectively removing the active layer 108 portions include laser ablation and plasma etching. Alternatively, the selective removal step could be obviated by prior selective deposition of the hole transport and active layers so as to leave minor portions of the anode exposed.

Separately, an encapsulation and interconnect sheet 170 as shown in Figure 3 is prepared, consisting of a flexible plastic substrate 172, on which barrier layers may optionally be deposited to reduce permeability to oxygen and water vapour, and on which conducting interconnect pads 171 are deposited by such techniques as sputtering, shadow evaporation or screen printing.

The completed device array 100 as shown in Figure 2 is then placed in contact with the interconnect/ encapsulation sheet 170 as shown in Figure 3, and laminated thereto, preferably under application of pressure or heat, or both, so as to laminate the two sheets together, as shown in Figure 4.

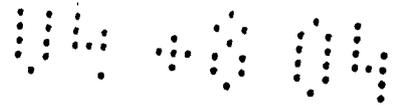
Thus, a complete laminated structure as shown in Figure 5 is produced, in which the interconnect pads 171 make contact with the cathodes 110 and exposed anode portions 104a of adjacent device cells, or with metallised tracks, of the device array. The plastic sheet 172 additionally protects the device array, to afford environmental protection and



increased robustness. The method is amenable to lamination by roll-to-roll manufacturing techniques, as illustrated in Figure 6.

Where the array is a solar cell array, series connection provides increased voltage output.

Where the array is an OLED array, the individual OLEDs may be used to form fixed images, simple moving displays such as an alphanumeric display or for lighting purposes.

**CLAIMS:**

1. A method of producing an encapsulated module of interconnected opto-electronic devices, comprising:

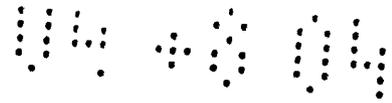
forming a patterned first electrode layer on a substrate in a pattern to define an array of first electrodes;

forming a layer of opto-electronically active material over said patterned first electrode layer on said substrate so as to overlie at least major portions of said first electrodes;

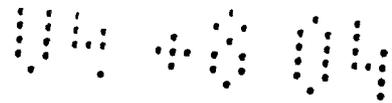
forming over said layer of opto-electronically active material a patterned second electrode layer having an opposite polarity to the first electrode in a pattern to define an array of second electrodes corresponding to said first electrode array, wherein said first electrodes, second electrodes and opto-electronically active material between said first and second electrodes define an array of opto-electronically active cells on said substrate; wherein said layer of opto-electronically active material and said patterned second electrode layer are so formed as to overlie a major portion of each first electrode and such that a minor portion of each first electrode is exposed and not overlain by said patterned layer of opto-electronically active material and said second electrode layer;

forming a patterned interconnect layer on an encapsulating sheet in a pattern to define an array of interconnect pads for interconnecting exposed first electrode portions with second electrodes of adjacent cells;

laminating said patterned encapsulating sheet over said array of opto-electronically active cells so as to bring said interconnect pad array into contact with exposed first electrode portions and second electrodes of adjacent cells whereby said exposed first electrode portions are interconnected with said second electrodes of said adjacent cells by said interconnect pads and said interconnected cells are encapsulated by said encapsulating sheet to form an encapsulated module.



2. A method according to claim 1, wherein said opto-electronically active layer is formed by spin-coating, spray coating, inkjet printing or screen printing.
3. A method according to claim 1 or 2, wherein said opto-electronically active material is deposited so as to overlie only said major portions of said first electrodes and leave minor portions of said first electrodes exposed.
4. A method according to claim 1 or 2, wherein said opto-electronically active material is deposited so as to overlie said major and minor portions of said first electrodes, and wherein the portions of said layer of opto-electronically active material that overlie said minor portions of said first electrodes are removed by laser ablation or plasma etching, before the lamination step, to expose said minor portions.
5. A method according to any preceding claim wherein the first electrode is an anode and the second electrode is a cathode.
6. A method according to claim 5, wherein said cathode layer is patterned using a shadow mask.
7. A method according to any preceding claim, wherein said patterned interconnect layer is formed on said encapsulating sheet by sputtering, shadow evaporation or screen printing.
8. A method according to any preceding claim, wherein said patterned encapsulating sheet is laminated over said array of opto-electronically active cells under pressure, heat or both.
9. A method according to any preceding claim, wherein said patterned encapsulating sheet is laminated over said array of opto-electronically active cells using an adhesive.
10. A method according to any preceding claim, wherein said patterned



encapsulating sheet is laminated over said array of opto-electronically active cells by a roll-to-roll manufacturing technique.

11. An encapsulated module of interconnected opto-electronic devices, comprising:

an array of opto-electronically active cells on a substrate, each cell comprising a first electrode layer formed on said substrate; a layer of opto-electronically active material formed over a major portion of said first electrode layer; a second electrode layer formed over said layer of opto-electronically active material and overlying a major portion of said first electrode layer whereby a minor portion of said first electrode layer is neither overlain by said layer of opto-electronically active material nor overlain by said second electrode layer; and

an encapsulating sheet having thereon an array of interconnects and laminated over said array of opto-electronically active cells;

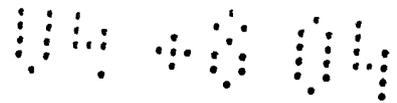
wherein said cells are interconnected by said interconnects contacting said minor first electrode portion of one cell and said second electrode layer of another cell.

12. An encapsulated module according to claim 11, wherein said opto-electronic device is an organic photovoltaic (PV) device or an organic light emitting diode (OLED) device.

13. An encapsulated module according to claim 11 or claim 12, wherein said encapsulating sheet is a flexible plastic sheet.

14. An encapsulated module according to claim 13, wherein said flexible encapsulating sheet is of poly(ethylene terephthalate) (PET) or poly(ethylene naphthalate) (PEN).

15. An encapsulated module according to any of claims 11 to 14, wherein said substrate is of glass or plastic, or is a glass/plastic laminate.



16. An encapsulated module according to any one of claims 11 to 15 wherein the first electrode is an anode and the second electrode is a cathode.
17. An encapsulated module according to claim 16, wherein said anode layer comprises indium tin oxide (ITO) and said cathode layer comprises one or more metallic layers.
18. An encapsulated module according to any of claims 11 to 17, wherein said interconnect pads are of a conductive material selected from aluminium, ITO, a colloidal metal and PEDOT:PSS.
19. An encapsulated module according to any of claims 11 to 18, wherein said cells are interconnected by said interconnect pads in series configuration.
20. An encapsulated module according to any of claims 11 to 18, wherein said cells are interconnected by said interconnect pads in parallel configuration.
21. An encapsulated module according to any of claims 11 to 18, wherein a portion of said cells are interconnected by said interconnect pads in series configuration and another portion of said cells are interconnected by said interconnect pads in parallel configuration.



INVESTOR IN PEOPLE

Application No: GB0416701.1

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Examiner: Mr Martyn Dixon

Claims searched: all

Date of search: 24 November 2004

Patents Act 1977: Search Report under Section 17

Documents considered to be relevant:

Category	Relevant to claims	Identity of document and passage or figure of particular relevance
A	-	WO2004/057674 A2 (Cambridge Display Technology) see e.g. page 4, lines 25-27; page 11, line 23 to page 12, line 4; page 12, lines 16-19; page 13, lines 14-16; page 14, lines 11-15
A	-	US5516704 A (Fuji Electric)

Categories:

X Document indicating lack of novelty or inventive step	A Document indicating technological background and/or state of the art.
Y Document indicating lack of inventive step if combined with one or more other documents of same category.	P Document published on or after the declared priority date but before the filing date of this invention.
& Member of the same patent family	E Patent document published on or after, but with priority date earlier than, the filing date of this application.

Field of Search:

Search of GB, EP, WO & US patent documents classified in the following areas of the UKC^W :

H1K

Worldwide search of patent documents classified in the following areas of the IPC⁰⁷

H01L; H05B

The following online and other databases have been used in the preparation of this search report

online: EPODOC, WPI, JAPIO